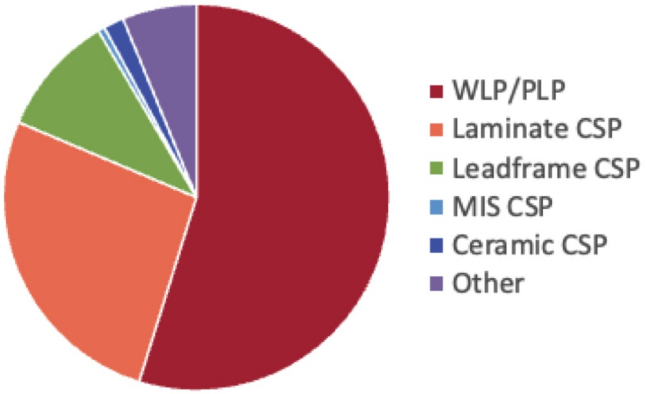
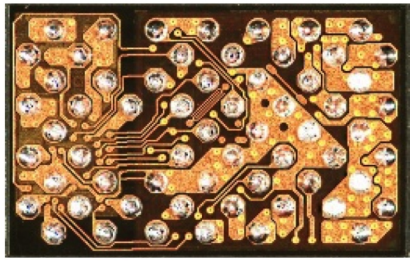
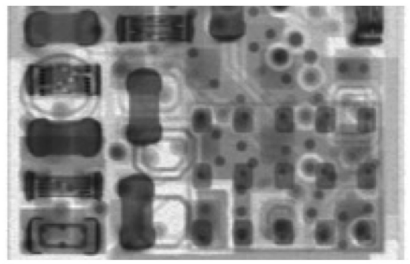
Apple iPhone 14 Pro

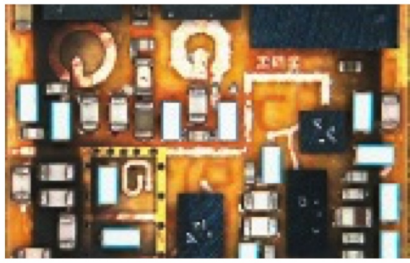
Teardown from TechSearch International, Inc.

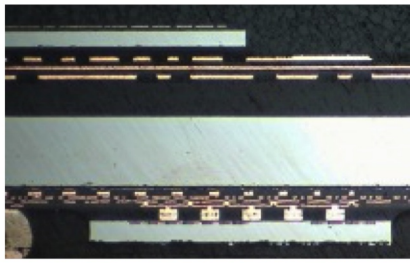
177 Packages Disassembled

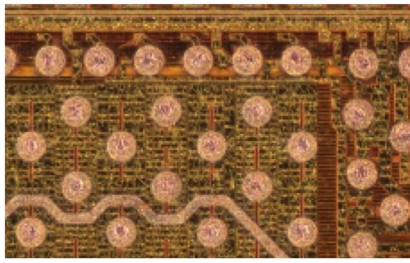


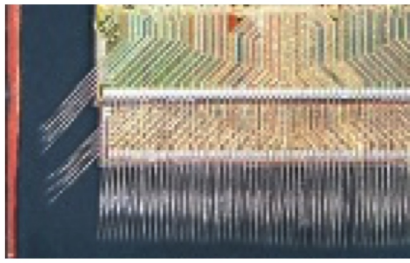












Contents and Highlights

- 208-page report with photos of packages (before and after decapsulation), x-rays, package dimensions, and die metrics and images
- 33 slides with extra details including cross sections, advanced packaging technology characteristics, and interesting finds
- Compared to iPhone 13 Pro, the 14 Pro has one additional package overall and a total of 11 more die
- Apple increase its use of FO-WLPs and molded WLPs
- Flip chip components represent a higher portion of the total die count

Teardowns backed by 35 years serving as the industry's trusted source for semiconductor packaging trend analysis

- Examination of all chips with emphasis on assembly and packaging technologies
- Superb quality photographs and x-ray images
- Both the packages and the die within are identified and characterized
- Detailed construction analysis of key chips and packages

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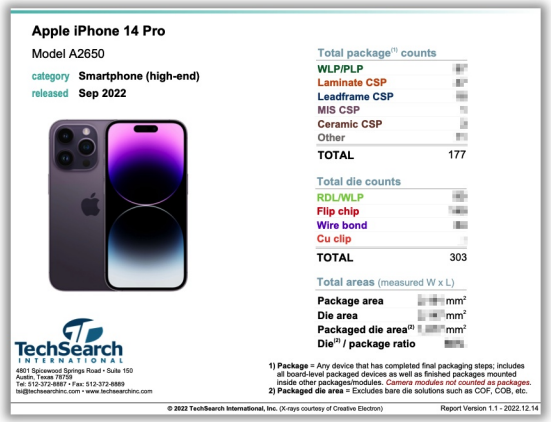
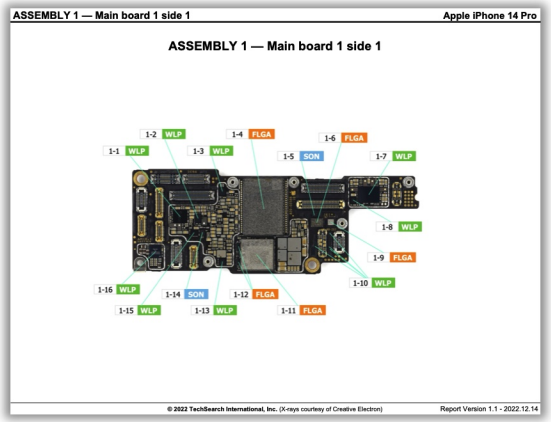
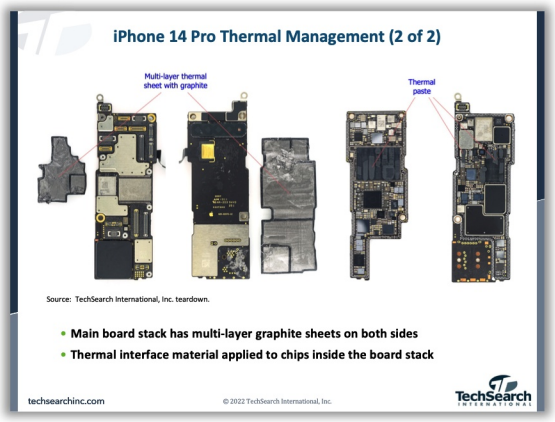
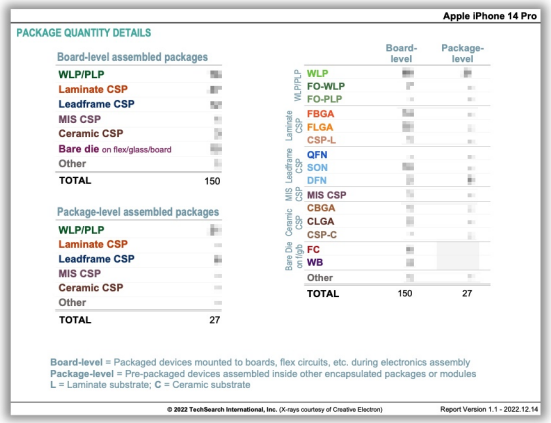
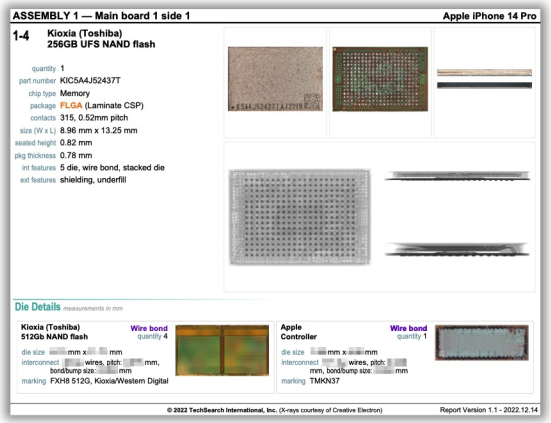
Sample pages from the report and slides

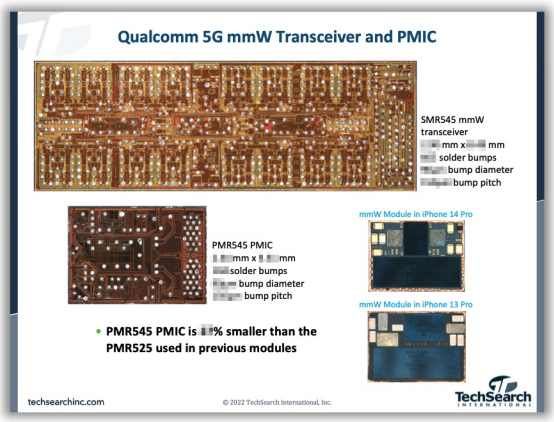


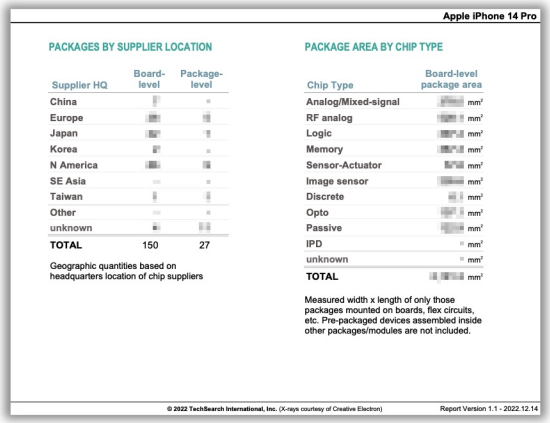


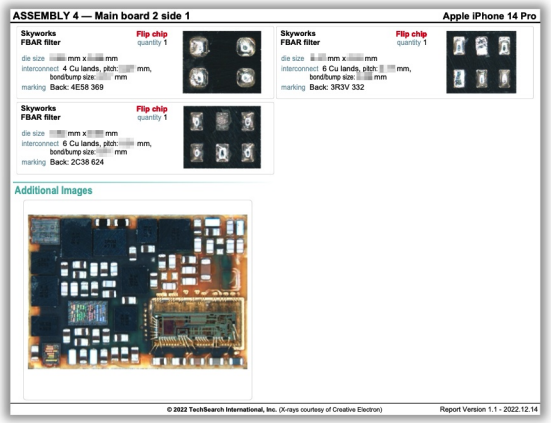


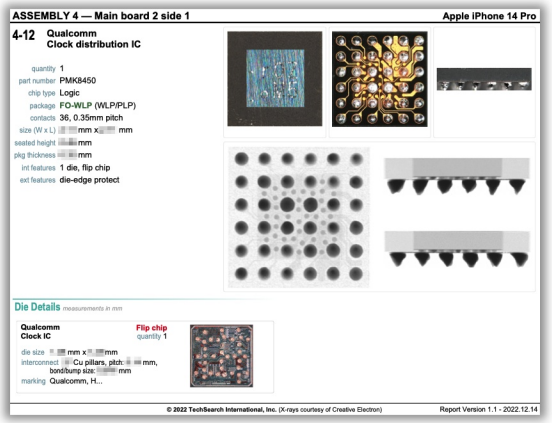












For pricing, please call +1-512-372-8887